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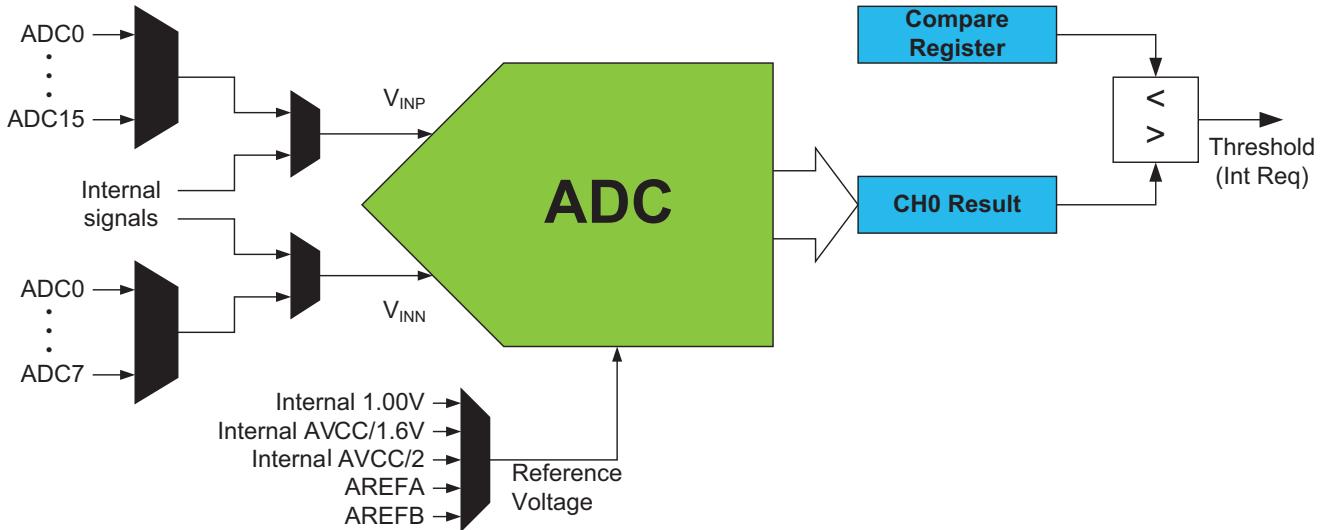
"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	AVR
Core Size	8/16-Bit
Speed	32MHz
Connectivity	I ² C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	50
Program Memory Size	32KB (16K x 16)
Program Memory Type	FLASH
EEPROM Size	1K x 8
RAM Size	4K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 3.6V
Data Converters	A/D 16x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-TQFP
Supplier Device Package	64-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/atxmega32d3-an

Figure 25-1. ADC Overview



The ADC may be configured for 8- or 12-bit result, reducing the minimum conversion time (propagation delay) from 3.35 μ s for 12-bit to 2.3 μ s for 8-bit result.

ADC conversion results are provided left- or right adjusted with optional '1' or '0' padding. This eases calculation when the result is represented as a signed integer (signed 16-bit number).

PORTA has one ADC. Notation of this peripheral is ADCA.

32.1.11 Power-on Reset Characteristics

Table 32-16. Power-on Reset Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
V_{POT^-} (1)	POR threshold voltage falling V_{CC}	V_{CC} falls faster than 1V/ms	0.4	1.0		V
		V_{CC} falls at 1V/ms or slower	0.8	1.3		
V_{POT^+}	POR threshold voltage rising V_{CC}			1.3	1.59	

Note: 1. V_{POT^-} values are only valid when BOD is disabled. When BOD is enabled $V_{POT^-} = V_{POT^+}$.

32.1.12 Flash and EEPROM Memory Characteristics

Table 32-17. Endurance and Data Retention

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
	Flash	Write/Erase cycles	25°C	10K		Cycle
			85°C	10K		
			105°C	2K		
		Data retention	25°C	100		Year
			85°C	25		
			105°C	10		
	EEPROM	Write/Erase cycles	25°C	100K		Cycle
			85°C	100K		
			105°C	30K		
		Data retention	25°C	100		Year
			85°C	25		
			105°C	10		

Table 32-18. Programming Time

Symbol	Parameter	Condition	Min.	Typ. (1)	Max.	Units
	Chip erase (2)	32KB Flash, EEPROM		50		ms
	Application erase	Section erase		6		
	Flash	Page erase		4		
		Page write		4		
		Atomic page erase and write		8		
	EEPROM	Page erase		4		
		Page write		4		
		Atomic page erase and write		8		

Notes: 1. Programming is timed from the 2MHz internal oscillator.
2. EEPROM is not erased if the EESAVE fuse is programmed.

32.2.3 Current Consumption

Table 32-33. Current Consumption for Active Mode and Sleep Modes

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{CC}	Active power consumption ⁽¹⁾	32kHz, Ext. Clk	$V_{CC} = 1.8V$	50		μA
			$V_{CC} = 3.0V$	130		
		1MHz, Ext. Clk	$V_{CC} = 1.8V$	215		μA
			$V_{CC} = 3.0V$	475		
		2MHz, Ext. Clk	$V_{CC} = 1.8V$	445	600	mA
			$V_{CC} = 3.0V$	0.95	1.5	
		32MHz, Ext. Clk		7.8	12.0	
	Idle power consumption ⁽¹⁾	32kHz, Ext. Clk	$V_{CC} = 1.8V$	2.8		μA
			$V_{CC} = 3.0V$	3		
		1MHz, Ext. Clk	$V_{CC} = 1.8V$	46		
			$V_{CC} = 3.0V$	92		
		2MHz, Ext. Clk	$V_{CC} = 1.8V$	93	225	mA
			$V_{CC} = 3.0V$	184	350	
		32MHz, Ext. Clk		2.9	5.0	
	Power-down power consumption	$T = 25^\circ C$		0.07	1.0	μA
		$T = 85^\circ C$	$V_{CC} = 3.0V$	1.3	5.0	
		$T = 105^\circ C$		4.0	8.0	
		WDT and sampled BOD enabled, $T = 25^\circ C$		1.3	2.0	
		WDT and sampled BOD enabled, $T = 85^\circ C$	$V_{CC} = 3.0V$	2.6	6.0	
		WDT and sampled BOD enabled, $T = 105^\circ C$		5.0	10	
	Power-save power consumption ⁽²⁾	RTC from ULP clock, WDT and sampled BOD enabled, $T = 25^\circ C$	$V_{CC} = 1.8V$	1.7		μA
			$V_{CC} = 3.0V$	1.8		
		RTC from 1.024kHz low power 32.768kHz TOSC, $T = 25^\circ C$	$V_{CC} = 1.8V$	0.5	2.0	
			$V_{CC} = 3.0V$	0.7	2.0	
		RTC from low power 32.768kHz TOSC, $T = 25^\circ C$	$V_{CC} = 1.8V$	0.9	3.0	mA
			$V_{CC} = 3.0V$	1.2	3.0	
	Reset power consumption	Current through \overline{RESET} pin subtracted	$V_{CC} = 3.0V$	120		

- Notes:
- All Power Reduction Registers set.
 - Maximum limits are based on characterization, and not tested in production.

Figure 32-36. Maximum Frequency vs. V_{CC}

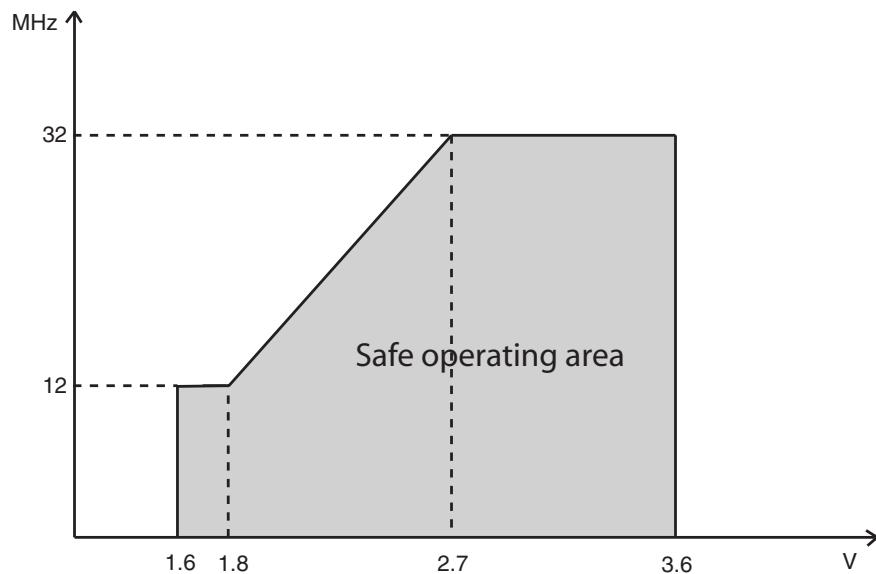


Table 32-155. Accuracy Characteristics

Symbol	Parameter	Condition ⁽¹⁾	Min.	Typ.	Max.	Units
RES	Resolution	12-bit resolution	Differential	8	12	12
			Single ended signed	7	11	11
			Single ended unsigned	8	12	12
INL ⁽²⁾	Integral non-linearity	Differential mode	16ksps, V _{REF} = 3V		0.5	1
			16ksps, all V _{REF}		0.8	2
			300ksps, V _{REF} = 3V		0.6	1
			300ksps, all V _{REF}		1	2
		Single ended unsigned mode	16ksps, V _{REF} = 3.0V		0.5	1
			16ksps, all V _{REF}		1.3	2
DNL ⁽²⁾	Differential non-linearity	Differential mode	16ksps, V _{REF} = 3V		0.3	1
			16ksps, all V _{REF}		0.5	1
			300ksps, V _{REF} = 3V		0.35	1
			300ksps, all V _{REF}		0.5	1
		Single ended unsigned mode	16ksps, V _{REF} = 3.0V		0.6	1
			16ksps, all V _{REF}		0.6	1
	Offset error	Differential mode	300ksps, V _{REF} = 3V		-7	mV
			Temperature drift, V _{REF} = 3V		0.01	mV/K
			Operating voltage drift		0.16	mV/V
	Gain error	Differential mode	External reference		-5	mV
			AV _{CC} /1.6		-5	
			AV _{CC} /2.0		-6	
			Bandgap		±10	
			Temperature drift		0.02	mV/K
			Operating voltage drift		2	mV/V
	Gain error	Single ended unsigned mode	External reference		-8	mV
			AV _{CC} /1.6		-8	
			AV _{CC} /2.0		-8	
			Bandgap		±10	
			Temperature drift		0.03	mV/K
			Operating voltage drift		2	mV/V

Notes: 1. Unless otherwise noted all linearity, offset and gain error numbers are valid under the condition that external V_{REF} is used.
 2. Maximum numbers are based on characterisation and not tested in production, and valid for 5% to 95% input voltage range.

32.6.8 Bandgap and Internal 1.0V Reference Characteristics

Table 32-158. Bandgap and Internal 1.0V Reference Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
	Startup time	As reference for ADC	1 Clk _{PER} + 2.5μs			μs
		As input voltage to ADC and AC		1.5		
	Bandgap voltage			1.1		V
INT1V	Internal 1.00V reference	T = 85°C, after calibration	0.99	1	1.01	
	Variation over voltage and temperature	Calibrated at T = 85°C		2		%

32.6.9 Brownout Detection Characteristics

Table 32-159. Brownout Detection Characteristics ⁽¹⁾

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
V _{BOT}	BOD level 0 falling V _{CC}		1.60	1.62	1.72	V
	BOD level 1 falling V _{CC}			1.9		
	BOD level 2 falling V _{CC}			2.0		
	BOD level 3 falling V _{CC}			2.2		
	BOD level 4 falling V _{CC}			2.4		
	BOD level 5 falling V _{CC}			2.6		
	BOD level 6 falling V _{CC}			2.8		
	BOD level 7 falling V _{CC}			3.0		
t _{BOD}	Detection time	Continuous mode		0.4		μs
		Sampled mode			1000	
V _{HYST}	Hysteresis			1.0		%

Note: 1. BOD is calibrated at 85°C within BOD level 0 values, and BOD level 0 is the default level.

32.6.10 External Reset Characteristics

Table 32-160. External Reset Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
t _{EXT}	Minimum reset pulse width		1000	90		ns
V _{RST}	Reset threshold voltage	V _{CC} = 2.7 - 3.6V		0.45 * V _{CC}		V
		V _{CC} = 1.6 - 2.7V		0.42 * V _{CC}		
R _{RST}	Reset pin pull-up resistor			25		kΩ

32.6.13.5 Internal Phase Locked Loop (PLL) Characteristics

Table 32-168. Internal PLL Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
f_{IN}	Input frequency	Output frequency must be within f_{OUT}	0.4		64	
f_{OUT}	Output frequency ⁽¹⁾	$V_{CC} = 1.6 - 1.8V$	20		48	MHz
		$V_{CC} = 2.7 - 3.6V$	20		128	
	Start-up time			25		μs
	Re-lock time			25		

Note: 1. The maximum output frequency vs. supply voltage is linear between 1.8V and 2.7V, and can never be higher than four times the maximum CPU frequency.

32.6.13.6 External Clock Characteristics

Figure 32-38. External Clock Drive Waveform

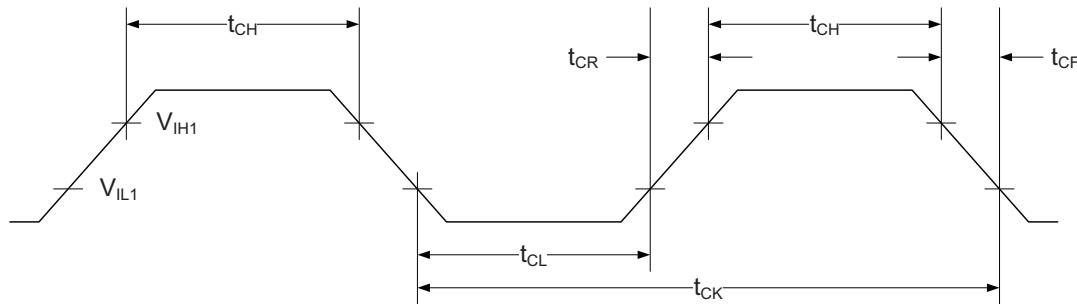


Table 32-169.External Clock used as System Clock without Prescaling

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$1/t_{CK}$	Clock Frequency ⁽¹⁾	$V_{CC} = 1.6 -$	0		12	MHz
		$V_{CC} = 2.7 -$	0		32	
t_{CK}	Clock Period	$V_{CC} = 1.6 -$	83.3			
		$V_{CC} = 2.7 -$	31.5			
t_{CH}	Clock High Time	$V_{CC} = 1.6 -$	30.0			
		$V_{CC} = 2.7 -$	12.5			
t_{CL}	Clock Low Time	$V_{CC} = 1.6 -$	30.0			
		$V_{CC} = 2.7 -$	12.5			
t_{CR}	Rise Time (for maximum frequency)	$V_{CC} = 1.6 -$			10	
		$V_{CC} = 2.7 -$			3	
t_{CF}	Fall Time (for maximum frequency)	$V_{CC} = 1.6 -$			10	
		$V_{CC} = 2.7 -$			3	
Δt_{CK}	Change in period from one clock cycle to the next				10	%

Note: 1. The maximum frequency vs. supply voltage is linear between 1.6V and 2.7V, and the same applies for all other parameters with supply voltage conditions.

Table 32-170.External Clock with Prescaler ⁽¹⁾ for System Clock

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$1/t_{CK}$	Clock Frequency ⁽²⁾	$V_{CC} = 1.6 - 1.8V$	0		90	MHz
		$V_{CC} = 2.7 - 3.6V$	0		142	
t_{CK}	Clock Period	$V_{CC} = 1.6 - 1.8V$	11			
		$V_{CC} = 2.7 - 3.6V$	7			
t_{CH}	Clock High Time	$V_{CC} = 1.6 - 1.8V$	4.5			
		$V_{CC} = 2.7 - 3.6V$	2.4			
t_{CL}	Clock Low Time	$V_{CC} = 1.6 - 1.8V$	4.5			ns
		$V_{CC} = 2.7 - 3.6V$	2.4			
t_{CR}	Rise Time (for maximum frequency)	$V_{CC} = 1.6 - 1.8V$			1.5	
		$V_{CC} = 2.7 - 3.6V$			1.0	
t_{CF}	Fall Time (for maximum frequency)	$V_{CC} = 1.6 - 1.8V$			1.5	
		$V_{CC} = 2.7 - 3.6V$			1.0	
Δt_{CK}	Change in period from one clock cycle to the next				10	%

Notes:

1. System Clock Prescalers must be set so that maximum CPU clock frequency for device is not exceeded.
2. The maximum frequency vs. supply voltage is linear between 1.6V and 2.7V, and the same applies for all other parameters with supply voltage conditions.

32.6.13.7 External 16MHz Crystal Oscillator and XOSC Characteristics

Table 32-171. External 16MHz Crystal Oscillator and XOSC Characteristics

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
	Cycle to cycle jitter	XOSCPWR=0	FRQRANGE=0		0	ns
			FRQRANGE=1, 2, or 3		0	
		XOSCPWR=1			0	
	Long term jitter	XOSCPWR=0	FRQRANGE=0		0	
			FRQRANGE=1, 2, or 3		0	
		XOSCPWR=1			0	
	Frequency error	XOSCPWR=0	FRQRANGE=0		0.03	%
			FRQRANGE=1		0.03	
			FRQRANGE=2 or 3		0.03	
		XOSCPWR=1			0.003	
	Duty cycle	XOSCPWR=0	FRQRANGE=0		50	%
			FRQRANGE=1		50	
			FRQRANGE=2 or 3		50	
		XOSCPWR=1			50	

33.2.7 External Reset Characteristics

Figure 33-120. Minimum Reset Pin Pulse Width vs. V_{cc}

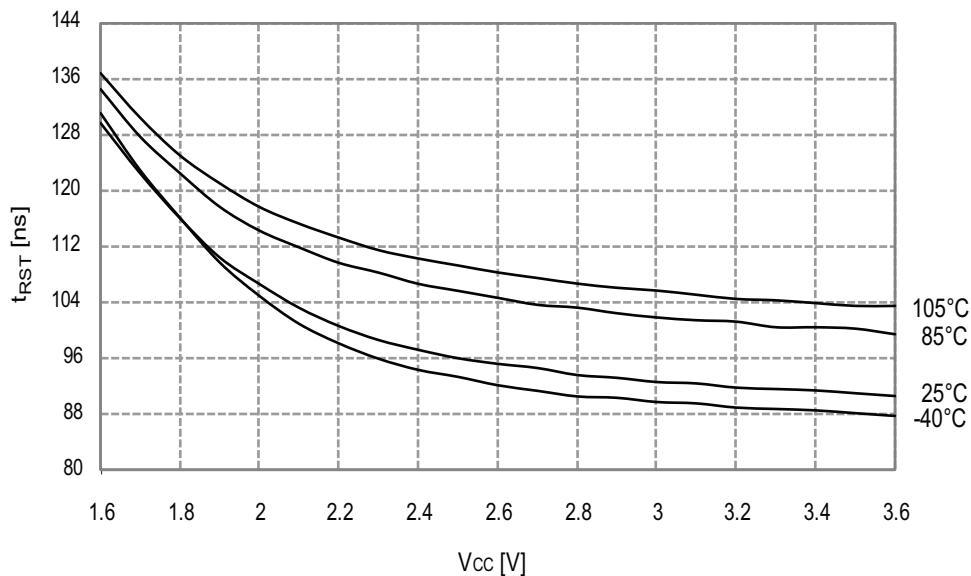


Figure 33-121. Reset Pin Pull-up Resistor Current vs. Reset Pin Voltage

$V_{CC} = 1.8V$

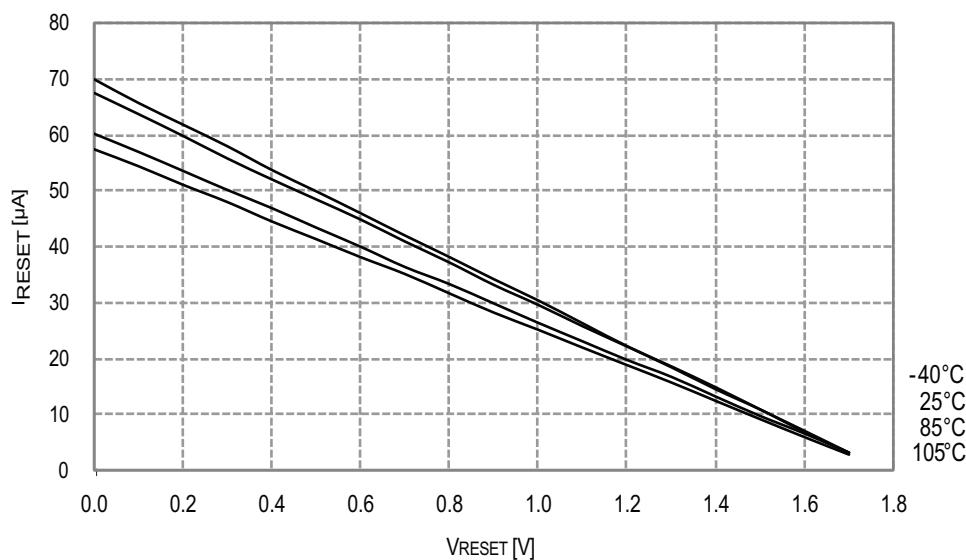


Figure 33-145. Active Mode Supply Current vs. V_{CC}

$f_{SYS} = 32.768\text{kHz}$ internal oscillator

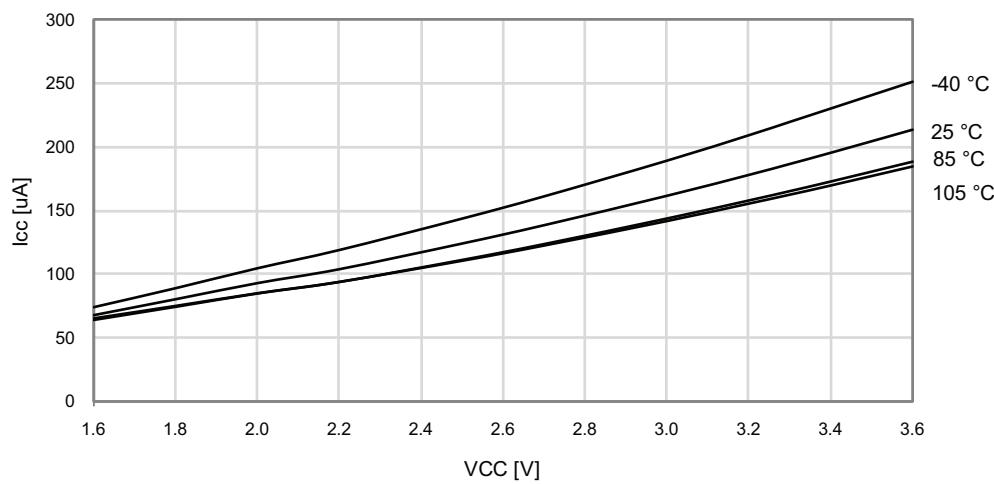


Figure 33-146. Active Mode Supply Current vs. V_{CC}

$f_{SYS} = 1\text{MHz}$ external clock

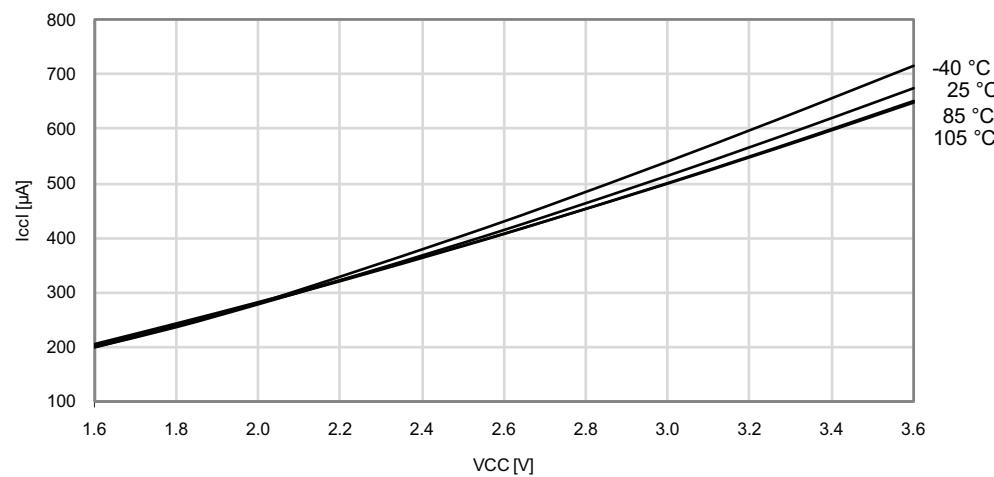
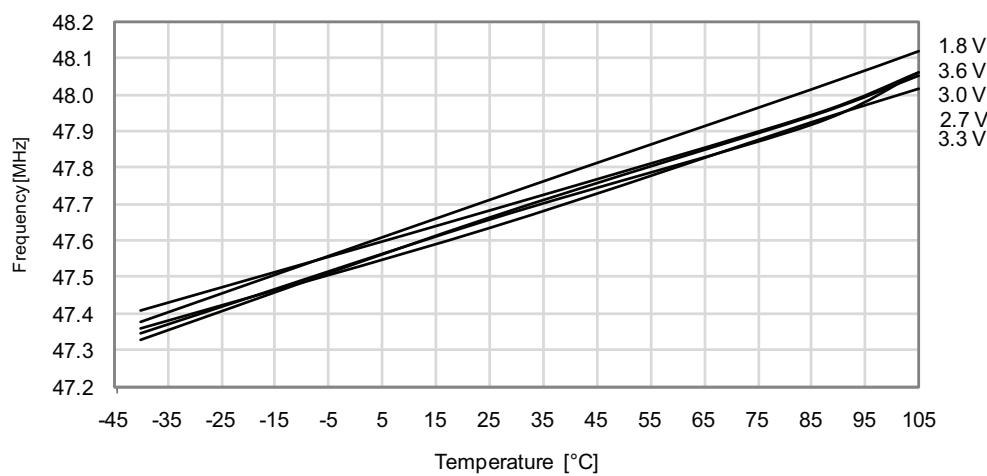


Figure 33-209. 48MHz Internal Oscillator Frequency vs. Temperature

DFLL enabled, from the 32.768kHz internal oscillator



33.3.9 Two-Wire Interface Characteristics

Figure 33-210. SDA Hold Time vs. Temperature

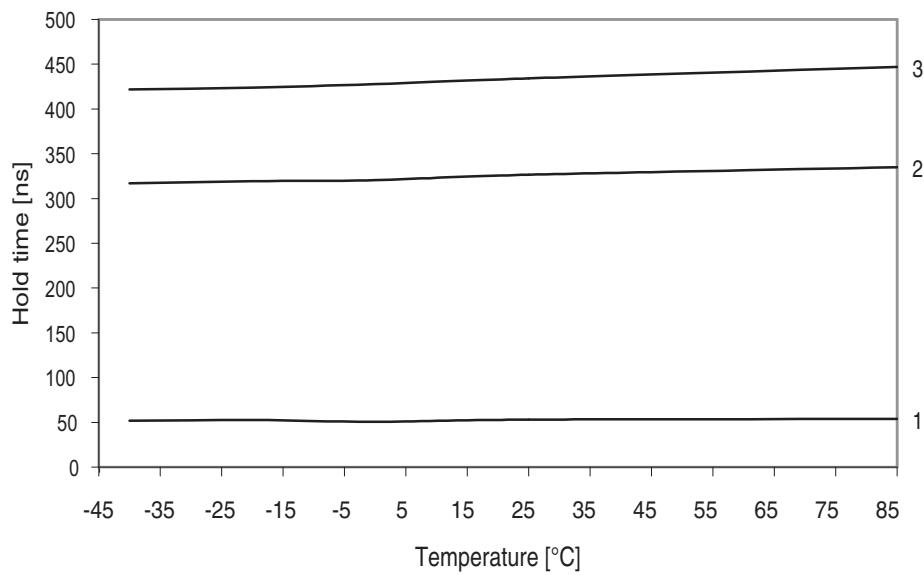


Figure 33-345. 32MHz Internal Oscillator CALA Calibration Step Size

$T = 85^\circ\text{C}$, $V_{CC} = 3.0\text{V}$

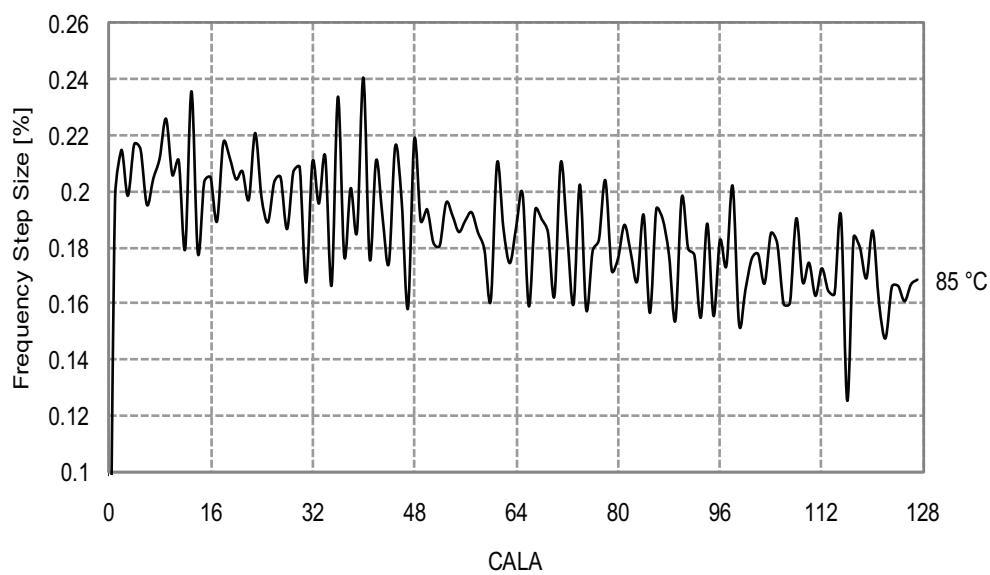


Figure 33-346. 32MHz Internal Oscillator CALA Calibration Step Size

$T = 105^\circ\text{C}$, $V_{CC} = 3.0\text{V}$

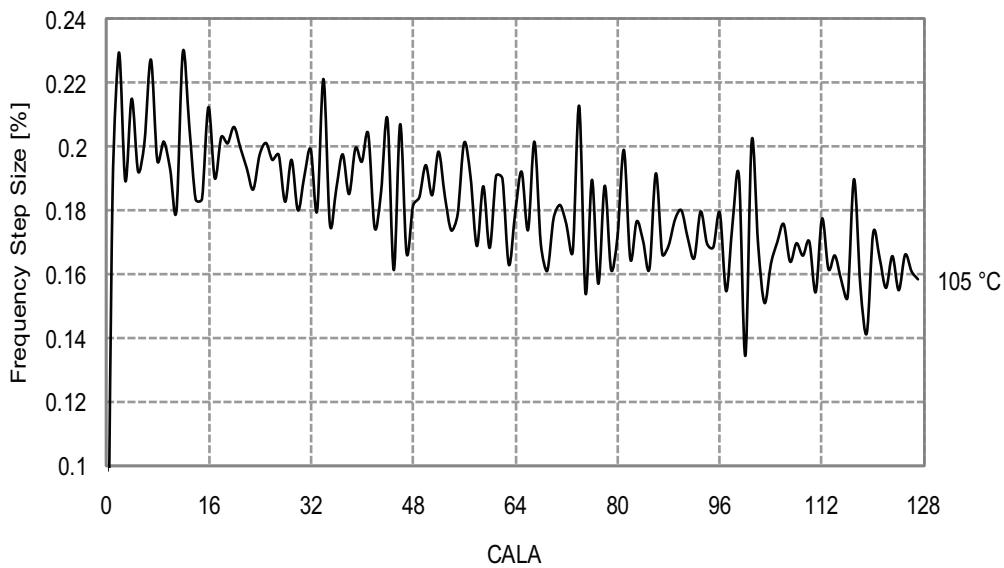
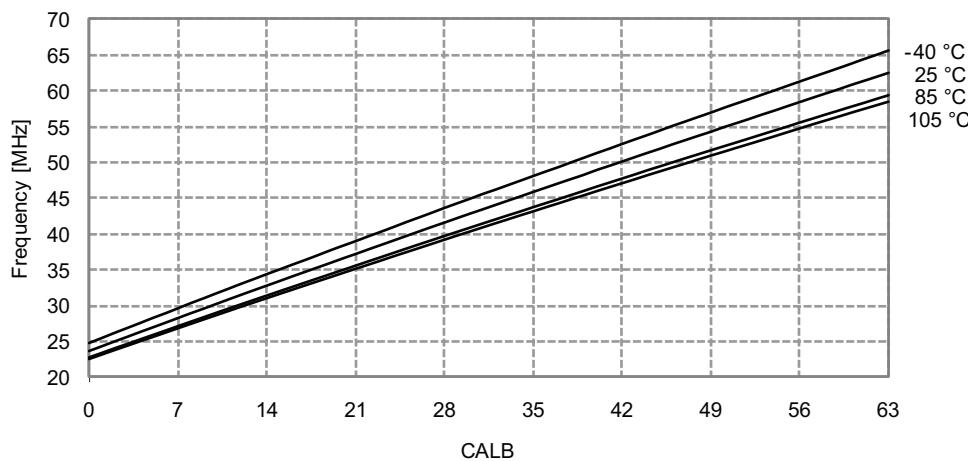


Figure 33-347. 32MHz Internal Oscillator Frequency vs. CALB Calibration Value

$V_{CC} = 3.0V$



33.5.8.5 32MHz Internal Oscillator Calibrated to 48MHz

Figure 33-348. 48MHz Internal Oscillator Frequency vs. Temperature

DFLL disabled

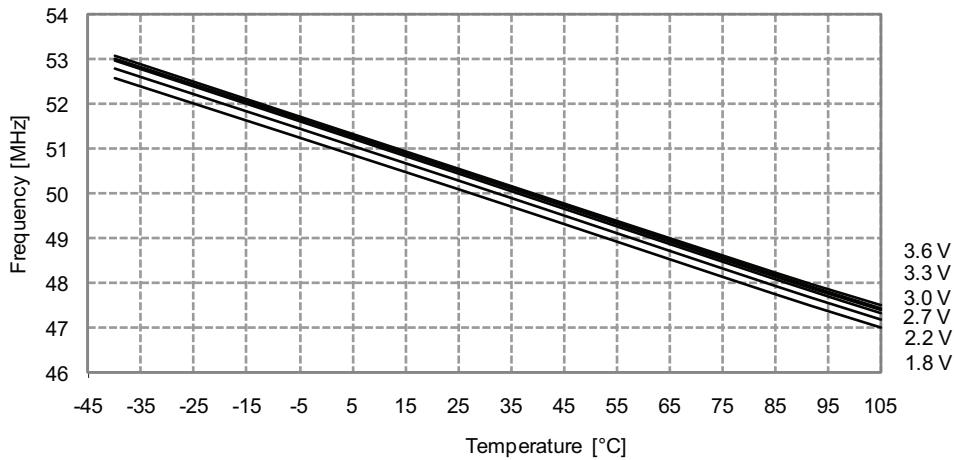


Figure 33-357.Active Mode Supply Current vs. V_{CC}

$f_{SYS} = 2MHz$ internal oscillator

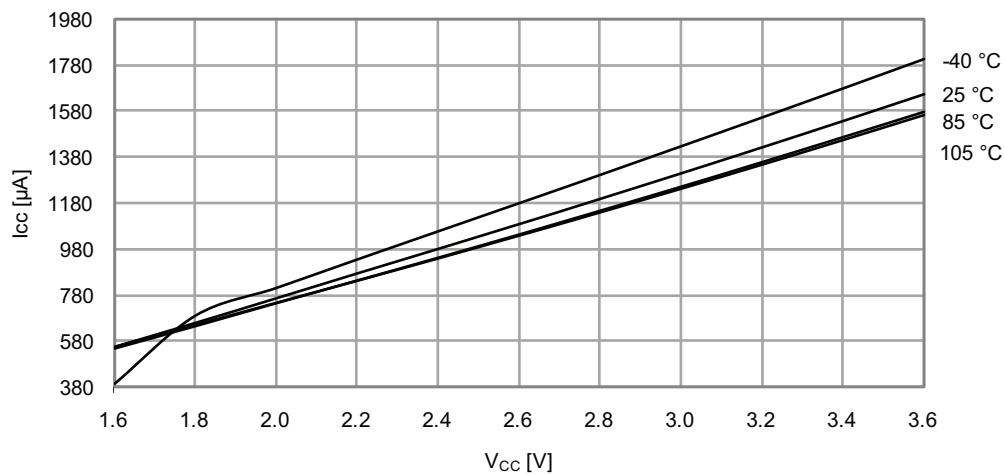


Figure 33-358.Active Mode Supply Current vs. V_{CC}

$f_{SYS} = 32MHz$ internal oscillator prescaled to 8MHz

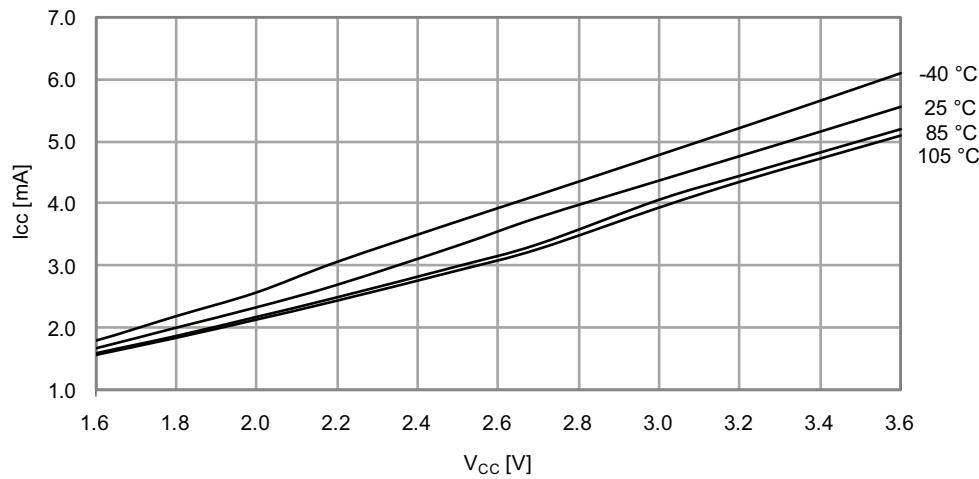


Figure 33-371.I/O Pin Pull-up Resistor Current vs. Input Voltage

$V_{CC} = 3.0V$

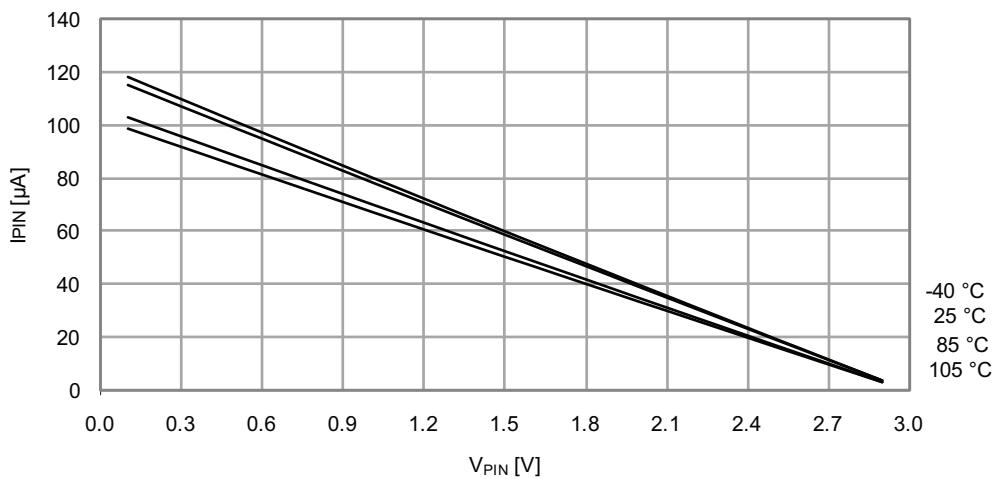
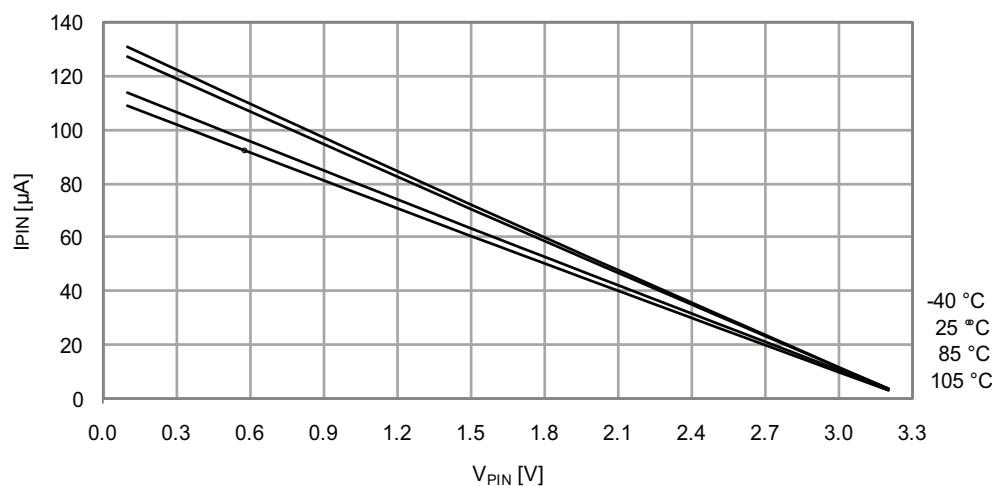


Figure 33-372.I/O Pin Pull-up Resistor Current vs. Input Voltage

$V_{CC} = 3.3V$



Problem fix/workaround

Table 34-1. Configure PWM and CWCM According to this Table:

PGM	CWCM	Description
0	0	PGM and CWCM disabled
0	1	PGM enabled
1	0	PGM and CWCM enabled
1	1	PGM enabled

11. PWM is not restarted properly after a fault in cycle-by-cycle mode

When the AWeX fault restore mode is set to cycle-by-cycle, the waveform output will not return to normal operation at first update after fault condition is no longer present.

Problem fix/workaround

Do a write to any AWeX I/O register to re-enable the output.

12. BOD will be enabled after any reset

If any reset source goes active, the BOD will be enabled and keep the device in reset if the V_{CC} voltage is below the programmed BOD level. During Power-On Reset, reset will not be released until V_{CC} is above the programmed BOD level even if the BOD is disabled.

Problem fix/workaround

Do not set the BOD level higher than V_{CC} even if the BOD is not used.

13. EEPROM page buffer always written when NVM DATA0 is written

If the EEPROM is memory mapped, writing to NVM DATA0 will corrupt data in the EEPROM page buffer.

Problem fix/workaround

Before writing to NVM DATA0, for example when doing software CRC or flash page buffer write, check if EEPROM page buffer active loading flag (EELOAD) is set. Do not write NVM DATA0 when EELOAD is set.

14. Pending full asynchronous pin change interrupts will not wake the device

Any full asynchronous pin-change Interrupt from pin 2, on any port, that is pending when the sleep instruction is executed, will be ignored until the device is woken from another source or the source triggers again. This applies when entering all sleep modes where the System Clock is stopped.

Problem fix/workaround

None.

15. Pin configuration does not affect Analog Comparator output

The Output/Pull and inverted pin configuration does not affect the Analog Comparator output.

Problem fix/workaround

None for Output/Pull configuration.

For inverted I/O, configure the Analog Comparator to give an inverted result (that is, connect positive input to the negative AC input and vice versa), or use an external inverter to change polarity of Analog Comparator output.

—	1×	gain:	2.4	V
—	2×	gain:	1.2	V
—	4×	gain:	0.6	V
—	8×	gain:	300	mV
—	16×	gain:	150	mV
—	32×	gain:	75	mV
—	64×	gain:	38	mV

Problem fix/workaround

Keep the amplified voltage output from the ADC gain stage below 2.4V in order to get a correct result, or keep ADC voltage reference below 2.4V.

6. ADC Event on compare match non-functional

ADC signalling event will be given at every conversion complete even if Interrupt mode (INTMODE) is set to BELOW or ABOVE.

Problem fix/workaround

Enable and use interrupt on compare match when using the compare function.

7. ADC propagation delay is not correct when 8× – 64× gain is used

The propagation delay will increase by only one ADC clock cycle for all gain settings.

Problem fix/workaround

None.

8. Bandgap measurement with the ADC is non-functional when V_{CC} is below 2.7V

The ADC can not be used to do bandgap measurements when V_{CC} is below 2.7V.

Problem fix/workaround

None.

9. Accuracy lost on first three samples after switching input to ADC gain stage

Due to memory effect in the ADC gain stage, the first three samples after changing input channel must be disregarded to achieve 12-bit accuracy.

Problem fix/workaround

Run three ADC conversions and discard these results after changing input channels to ADC gain stage.

10. Configuration of PGM and CWCM not as described in XMEGA D Manual

Enabling Common Waveform Channel Mode will enable Pattern generation mode (PGM), but not Common Waveform Channel Mode.

Enabling Pattern Generation Mode (PGM) and not Common Waveform Channel Mode (CWCM) will enable both Pattern Generation Mode and Common Waveform Channel Mode.

Problem fix/workaround

Table 34-6. Configure PWM and CWCM According to this Table:

PGM	CWCM	Description
0	0	PGM and CWCM disabled
0	1	PGM enabled
1	0	PGM and CWCM enabled
1	1	PGM enabled

11. PWM is not restarted properly after a fault in cycle-by-cycle mode

When the AWeX fault restore mode is set to cycle-by-cycle, the waveform output will not return to normal operation at first update after fault condition is no longer present.

Problem fix/workaround

Do a write to any AWeX I/O register to re-enable the output.

12. BOD will be enabled after any reset

If any reset source goes active, the BOD will be enabled and keep the device in reset if the V_{CC} voltage is below the programmed BOD level. During Power-On Reset, reset will not be released until V_{CC} is above the programmed BOD level even if the BOD is disabled.

Problem fix/workaround

Do not set the BOD level higher than V_{CC} even if the BOD is not used.

13. EEPROM page buffer always written when NVM DATA0 is written

If the EEPROM is memory mapped, writing to NVM DATA0 will corrupt data in the EEPROM page buffer.

Problem fix/workaround

Before writing to NVM DATA0, for example when doing software CRC or flash page buffer write, check if EEPROM page buffer active loading flag (EELOAD) is set. Do not write NVM DATA0 when EELOAD is set.

14. Pending full asynchronous pin change interrupts will not wake the device

Any full asynchronous pin-change Interrupt from pin 2, on any port, that is pending when the sleep instruction is executed, will be ignored until the device is woken from another source or the source triggers again. This applies when entering all sleep modes where the System Clock is stopped.

Problem fix/workaround

None.

15. Pin configuration does not affect Analog Comparator output

The Output/Pull and inverted pin configuration does not affect the Analog Comparator output.

Problem fix/workaround

None for Output/Pull configuration.

For inverted I/O, configure the Analog Comparator to give an inverted result (that is, connect positive input to the negative AC input and vice versa), or use an external inverter to change polarity of Analog Comparator output.

25. Non available functions and options

The below function and options are not available. Writing to any registers or fuse to try and enable or configure these functions or options will have no effect, and will be as writing to a reserved address location.

- TWIE, the TWI module on PORTE
- TWI SDAHOLD option in the TWI CTRL register is one bit
- CRC generator module
- ADC 1/2 \times gain option, and this configuration option in the GAIN bits in the ADC Channel CTRL register
- ADC VCC/2 reference option and this configuration option in the REFSEL bits on the ADC REFCTRL register
- ADC option to use internal Gnd as negative input in differential measurements and this configuration option in the MUXNEG bits in the ADC Channel MUXCTRL register
- ADC channel scan and the ADC SCAN register
- ADC current limitation option, and the CURRLIMIT bits in the ADC CTRLB register
- ADC impedance mode selection for the gain stage, and the IMPMODE bit in the ADC CTRLB register
- Timer/Counter 2 and the SPLITMODE configuration option in the BYTEM bits in the Timer/Counter 0 CTRLE register
- Analog Comparator (AC) current output option, and the AC CURRCTRL and CURRCALIB registers
- PORT remap functions with alternate pin locations for Timer/Counter output compare channels, USART0 and SPI, and the PORT REMAP register
- PORT RTC clock output option and the RTCOUT bit in the PORT CLKEVOUT register
- PORT remap functions with alternate pin locations for the clock and event output, and the CLKEVPIN bit in the PORT CLKEVOUT register
- TOSC alternate pin locations, and TOSCSEL bit in FUSEBYTE2
- Real Time Counter clock source options of external clock from TOSC1, and 32.768kHz from TOSC, and 32.768kHz from the 32.768kHz internal oscillator, and these configuration options in the RTCSRC bits in the Clock RTCTRL register
- PLL divide by two option, and the PLLDIV bit in the Clock PLLCTRL register
- PLL lock detection failure function and the PLLDIF and PLLFDEN bits in the Clock XOSCFAIL register
- The high drive option for external crystal and the XOSCPWR bit on the Oscillator XOSCCTRL register
- The option to enable sequential startup of the analog modules and the ANAINIT register in MCU Control memory

Problem fix/workaround

None.

26. Sampled BOD in Active mode will cause noise when bandgap is used as reference

Using the BOD in sampled mode when the device is running in Active or Idle mode will add noise on the bandgap reference for ADC, DAC and Analog Comparator.

Problem fix/workaround

If the bandgap is used as reference for either the ADC, DAC and Analog Comparator, the BOD must not be set in sampled mode.

27. Temperature sensor not calibrated

Temperature sensor factory calibration not implemented.

Problem fix/workaround

None.

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